

Matt Tin SAT 20 1

Matt Tin SAT 20 1 is a sulphate-free electrolyte depositing fine crystalline coatings. A good covering power and less sensitive to bleeding of alkali soluble plating resists are the special features of this process. Therefore, it is ideal as a metal resist in PCB manufacturing.

Anode solubility in systems based on the Acid Concentrate FF is much higher than in sulphuric acid based processes, so the electrolyte is of use when anode passivation occurs in a matt tin sulphate electrolyte.

Matt Tin SAT 20 1 is easy to operate and to maintain. Only monitoring the concentrations of tin(II) and acid is necessary, additive consumption is mainly due to drag-out.

If Tin Additive SAT 26 is used, the electrolyte is operated with methanol-free additives.

The information in this data sheet is based on laboratory as well as practical experience. Figures quoted for operating limits and replenishment quantities are for guidance only. Actual values necessary will depend on the components being plated (material and geometry), their application and plating plant conditions.

Important:

Please read this instruction carefully prior to the use of the process and carefully follow all the parameters that have a direct influence on the operation. We reserve the right to make technical changes. In the interest of safety, please pay attention to the hazard warnings on the labels of the containers. The minimum shelf life of the products is included on the labels and is also available in the appropriate Quality Assurance (QA03).

The current IMDS number of the layer deposited from the process is available on the internet at www.schloetter.com/downloads.

For the storage of chemical products the TRGS 510 must be followed.

If the additives used in this process contain a SVHC-substance, then this will be specified in the corresponding Material Safety Data Sheet, section 15.

